Welcome to E-XFL.COM

Understanding Embedded - Microcontroller, Microprocessor, FPGA Modules

Embedded - Microcontroller, Microprocessor, and FPGA Modules are fundamental components in modern electronic systems, offering a wide range of functionalities and capabilities. Microcontrollers are compact integrated circuits designed to execute specific control tasks within an embedded system. They typically include a processor, memory, and input/output peripherals on a single chip. Microprocessors, on the other hand, are more powerful processing units used in complex computing tasks, often requiring external memory and peripherals. FPGAs (Field Programmable Gate Arrays) are highly flexible devices that can be configured by the user to perform specific logic functions, making them invaluable in applications requiring customization and adaptability.

Applications of Embedded - Microcontroller,

Details	
Product Status	Obsolete
Module/Board Type	MCU, FPGA
Core Processor	ARM Cortex-A9
Co-Processor	Zynq-7000 (Z-7015)
Speed	125MHz
Flash Size	32MB
RAM Size	1GB
Connector Type	Samtec LSHM
Size / Dimension	1.97" x 1.57" (50mm x 40mm)
Operating Temperature	-40°C ~ 85°C
Purchase URL	https://www.e-xfl.com/product-detail/trenz-electronic/te0715-04-15-1i3

Overview

The Trenz Electronic TE0803 is an industrial-grade MPSoC module integrating a Xilinx Zynq UltraScale+ with up to 8 GByte 64-Bit width DDR4 SDRAM, and max. 512 MByte SPI Boot Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking connections.

All this in a compact 5.2 x 7.6 cm form factor, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

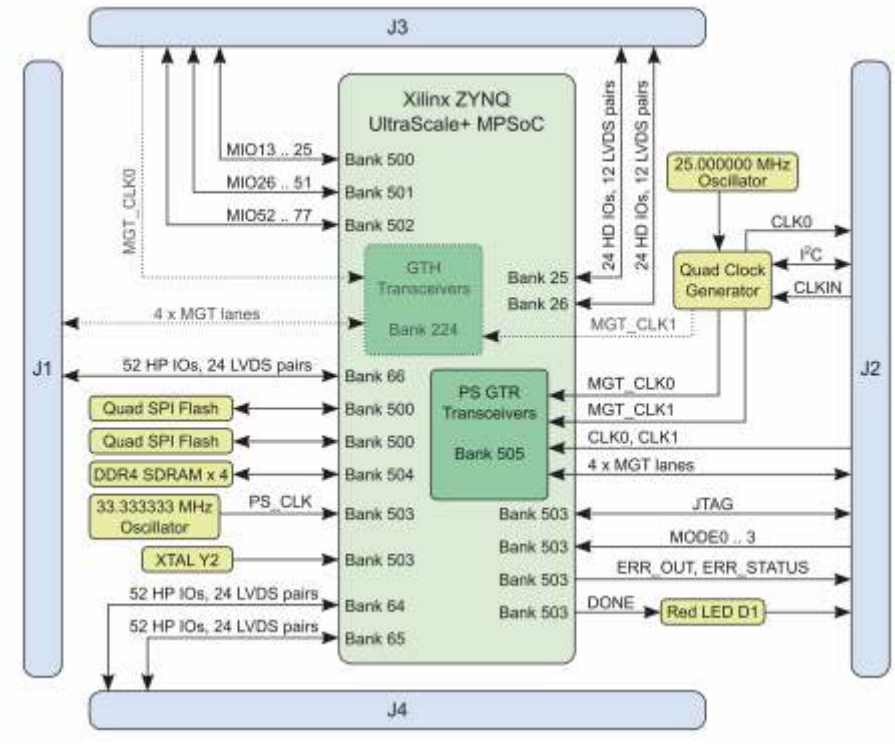
Rugged for industrial applications

XILINX ALL PROGRAMMABLE™

ZYNQ UltraSCALE+

Key Features (preliminary)

- Xilinx Zynq UltraScale+ MPSoC 784 pin package (ZU3EG, optional ZU5EV)
- Memory:
  - 64-Bit DDR4 - 8 GByte max
  - SPI Boot Flash dual parallel - 512 MByte max
- B2B connectors:
  Plug-on module with 4 x 160-pin connectors
  - 65 x MIO, 156 I/O's x HP (3 banks)
  - Serial transceiver: PS GTR 4, PL GT 4 (ZU4, ZU5 only)
  - GT Reference clock input
  - PLL for GT Clocks (optional external reference)
- Size: 52 x 76 mm
- All power supplies on board.
- Other assembly options for cost or performance optimization plus high volume prices available on request.



TEB0911 Series
Xilinx Zynq UltraScale+, 6 FMC Solts, Gigabit Ethernet

Key Features

- Zynq UltraScale+ MPSoC - 1156 Package ZU9 (ZU6, ZU9, ZU15 Possible as assembly option)
- 64-Bit DDR4 SODIMM (PS connected)
- PS-GTR
  - M2 PCIe SSD (internal, 1-Lane)
  - 2 x USB3 Host (from 4 port internal HUB)
  - 2 Lane DisplayPort output - Monitor
- RJ45 GbE Ethernet PS connected, 88E1512 PHY
- 4 x FMC-HPC connector front
  - 4 GTH
  - 1 GT Clock
  - 68+4 HP or HD I/O
- FMC-HPC connector Back
  - 4 GTH
  - 1 GT Clock
  - 12 I/O
- FMC-HPC connector Back
  - 1 GTH
  - 1 GT Clock
  - 12 I/O
- 2 x SFP+ connected to 2 PL GTH,
- 1 x SFP+ connected to PL GTH
- Power: 24V

Overview

The Trenz Electronic TEB0911 "UltraRack+" is a high performance Zynq UltraScale+ MPSoC board with 6 FMC slots and Gigabit Ethernet.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

XILINX ALL PROGRAMMABLE™

ZYNQ® UltraSCALE+

TE0808 UltraSOM+ Series
Xilinx Zynq UltraScale+, DDR4, Flash, 20 x Transceiver

5.2 x 7.6 form factor

Overview

The Trenz Electronic TE0808 is an industrial-grade MPSoC module integrating a Xilinx Zynq UltraScale+, max. 8 GByte DDR4 SDRAM with 64-Bit width, max. 512 MByte Flash memory for configuration and operation, 20 Gigabit transceivers, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking connections.

All this in a compact 5.2 x 7.6 cm form factor, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany

Key Features

- SoC: ZYNQ UltraScale+ ZU9EG 900 pin package
- Memory
  - 4 x 512 MByte 64-Bit DDR4 (8 GByte max.)
  - 2 x 32 MByte SPI Boot Flash dual parallel (512 MByte max.)
- User I/O
  - 65 x MIO, 48 x HD (all), 156 x HP (3 banks)
  - Serial transceiver: GTR 4 (all) + GTH 16 (all)
  - GT clocks, I2C
  - PLL clock inputs and outputs
- Size: 52 x 76 mm
- 3 mm mounting holes for skyline heat spreader
- B2B connectors: 4 x 160 pin
- Si5345 - 10 output PLL
- All power supplies on board, single 3.3V Power required
  - 14 on-board DC/DC regulators and 13 LDO's
  - LP, FP, PL separately controlled power domains
- Support for all boot modes (except NAND) and scenarios
- Support for any combination of PS connected peripherals

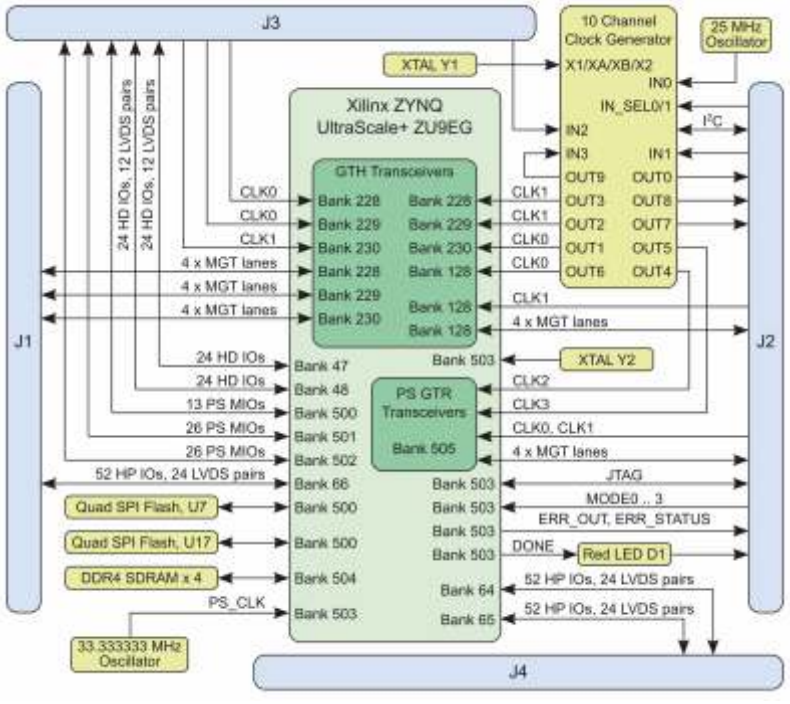
Other assembly options for cost or performance optimization plus high volume prices available on request.

Extended device life cycle

Rugged for industrial applications

XILINX ALL PROGRAMMABLE™

ZYNQ UltraSCALE+



www.trenz-electronic.de/te0808

TEC0330 Virtex-7 PCIe FMC Carrier

Overview

Trenz Electronic TEC0330 is an 8 lanes PCIe GEN2 Card integrating a high performance Xilinx Virtex-7 330T FPGA with 32 MByte Flash memory for configuration and operation, DDR3 SODIMM Socket and full FMC HPC connector for FPGA Mezzanine Cards.

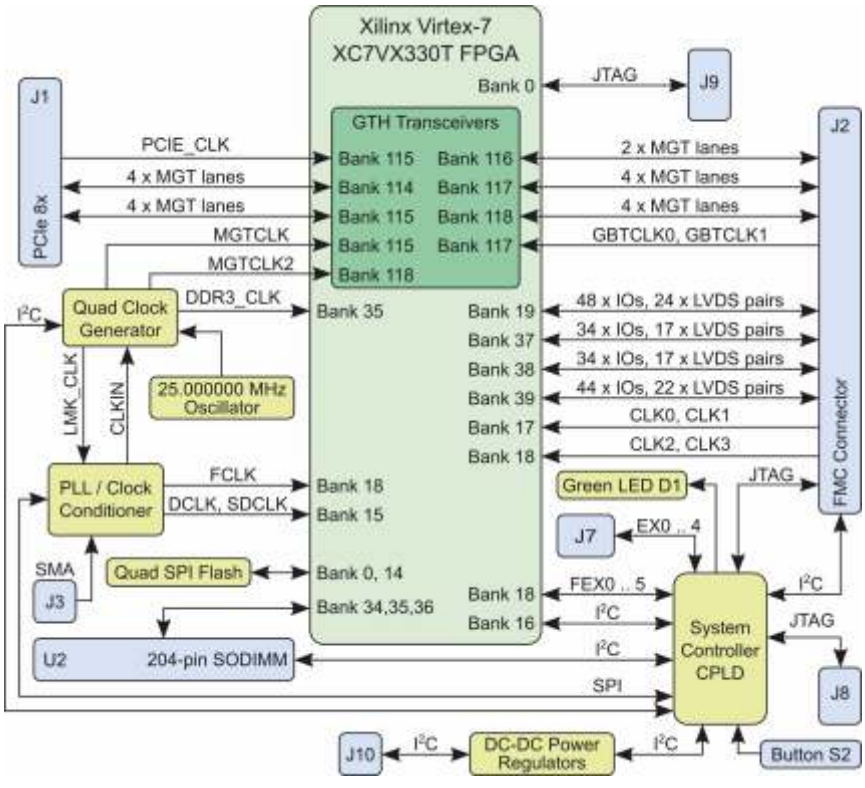
All modules produced by Trenz Electronic are developed and manufactured in Germany.

XILINX ALL PROGRAMMABLE™ VIRTEX 7

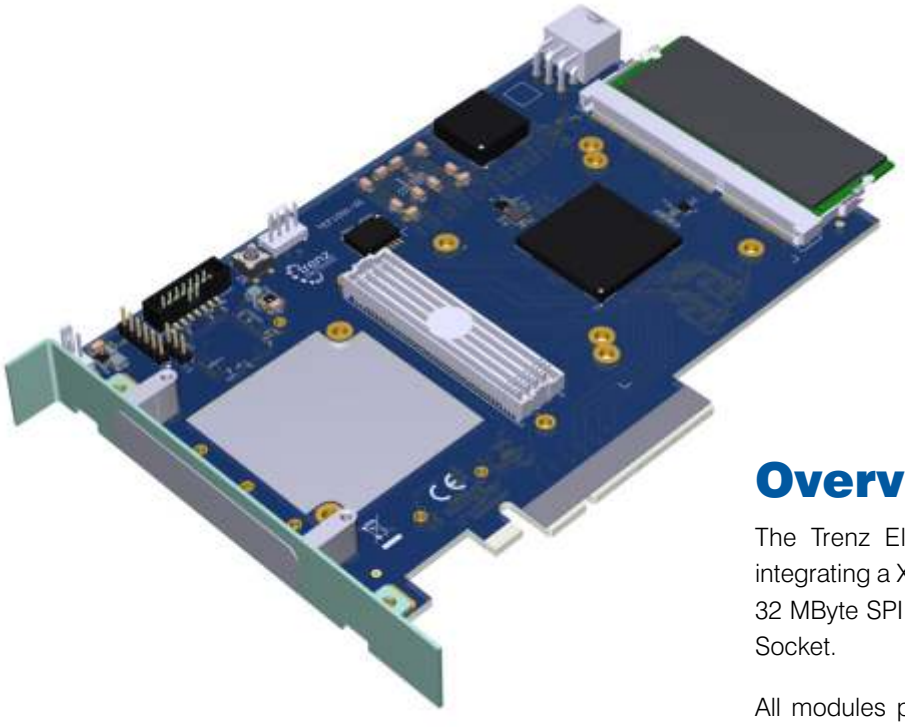
Key Features

- FMC HPC
- 8 lane PCIe Gen 2 capable
- Xilinx Virtex-7 XC7VX330T-2FFG1157C
- DDR3 SODIMM Socket
- 32 MByte SPI Flash
- LMK04828B Clock Synthesizer
- External Clock Input

Other assembly options for cost or performance optimization plus high volume prices available on request.



TEF1001 Series
PCIe FMC Carrier, Xilinx Kintex-7, SPI Flash, 4 lane PCIe



Overview

The Trenz Electronic TEF1001 is a PCIe FMC Carrier integrating a Xilinx Kintex-7 FPGA (K160T, K325T or K410T), 32 MByte SPI Flash, an 4 lane PCIe and a DDR3 SODIMM Socket.

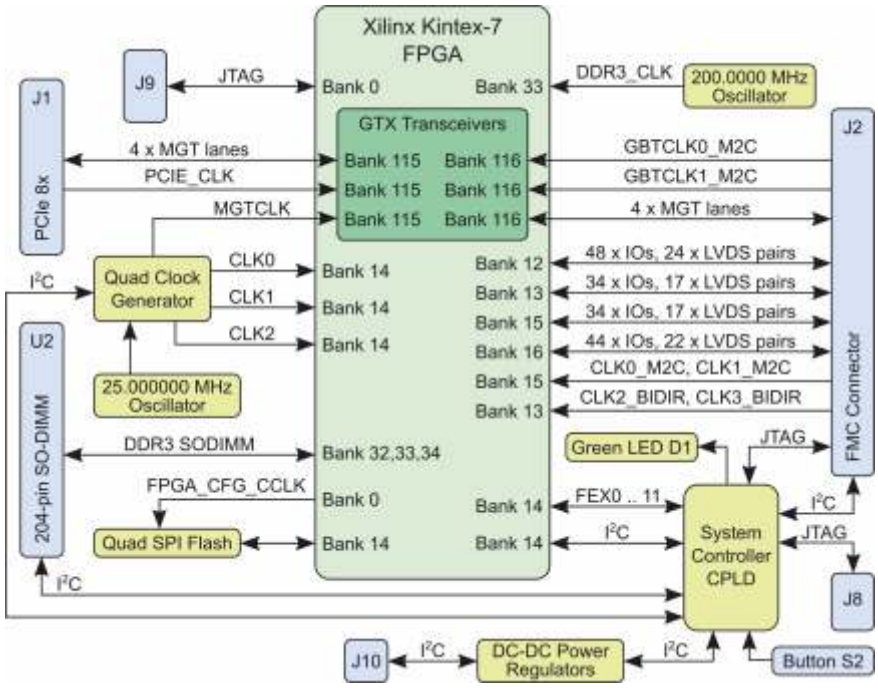
All modules produced by Trenz Electronic are developed and manufactured in Germany.

XILINX ALL PROGRAMMABLE™ KINTEX 7™

Key Features

- One Vita 57.1 FMC HPC Slot
- 4 lane PCIe Gen 2
- Xilinx Kintex-7 XC7K160T-2FBG676I
- DDR3 SODIMM Socket
- 32 MByte SPI Flash
- Programmable clock generator Si5338
- 200 MHz Low-Jitter LVDS oscillator
- High performance DC-DC converters

Other assembly options for cost or performance optimization plus high volume prices available on request.



TE0715 Series

Xilinx Zynq, Cortex-A9, DDR3, Flash, GBit Ethernet, 4 x Transceiver

Overview

Trenz Electronic TE0715 are industrial-grade SoC modules integrating a Xilinx Zynq-7000 SoC, a gigabit Ethernet transceiver (physical layer), 1 gigabyte DDR3 SDRAM with 32-Bit width, 32 megabyte Flash memory for configuration and operation, 4 transceivers, a USB ULPI transceiver, and powerful switch-mode power supplies for all onboard voltages. A large number of configurable I/O's is provided via rugged high-speed stacking strips. All modules in 4 x 5 cm form factor are mechanically compatible.
All this on a tiny footprint, smaller than a credit card, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

Rugged for industrial applications

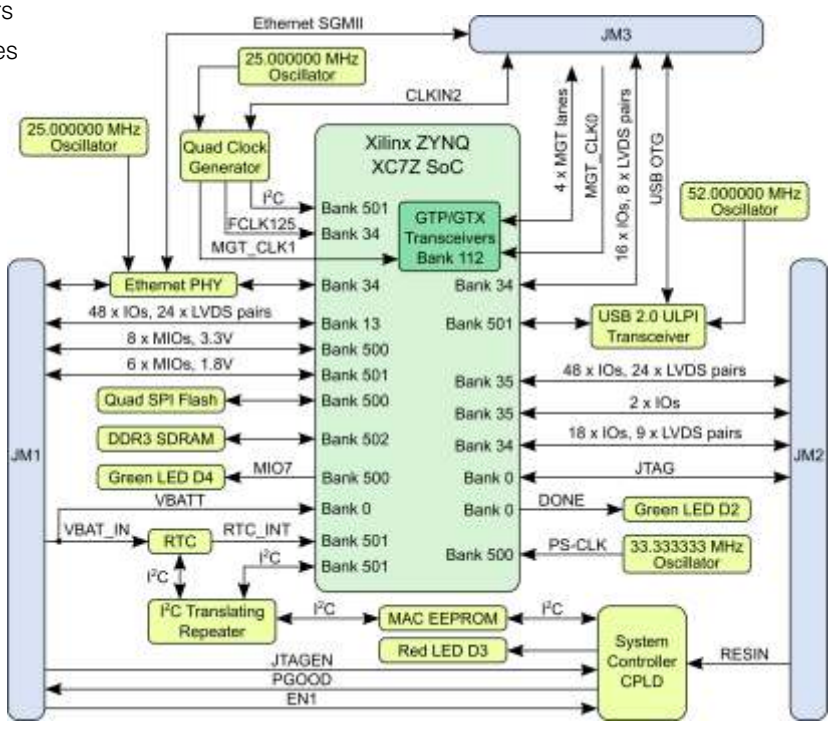
XILINX ALL PROGRAMMABLE™

ZYNQ™

Key Features

- Industrial-grade Xilinx Zynq-7000 (Z-7015, Z-7030) SoM , supported by the free Xilinx Vivado WebPACK tool
- Rugged for shock and high vibration
- ARM dual-core Cortex-A9
- 10/100/1000 tri-speed gigabit Ethernet transceiver (PHY) with SGMII
  - MAC Address EEPROM
- 32-Bit-wide 1 GByte DDR3 SDRAM
- 32 MByte QSPI Flash memory (with XiP support)
- Programmable clock generator
  - Transceiver clock (default 125 MHz)
- Plug-on module with 2 × 100-pin and 1 × 60-pin high-speed hermaphroditic strips
- 132 FPGA I/O's (65 LVDS pairs possible) and 14 PS-MIO available on board-to-board connectors
- 4 GTP/GTX (high-performance transceiver) lanes GTP/GTX (high-performance transceiver) clock input
- USB 2.0 high-speed ULPI transceiver
- On-board high-efficiency DC-DC converters
  - 4.0 A x 1.0 V power rail
  - 1.5 A x 1.5 V power rail
  - 1.5 A x 1.8 V power rail
- System management
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Temperature compensated RTC (real-time clock)
- User LED
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0715

TE0720 Series

Xilinx Zynq, 2 × Cortex-A9, DDR3, Flash, GBit Ethernet, USB

Overview

Trenz Electronic TE0720 are industrial-grade SoC modules integrating a Xilinx Zynq-7000 SoC, a gigabit Ethernet transceiver, 1 gigabyte DDR3 SDRAM with 32-Bit width, 32 megabyte Flash memory for configuration and operation, a USB ULPI transceiver, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking strips. All modules in 4 x 5 cm form factor are mechanically compatible.
All this on a tiny footprint, smaller than a credit card, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

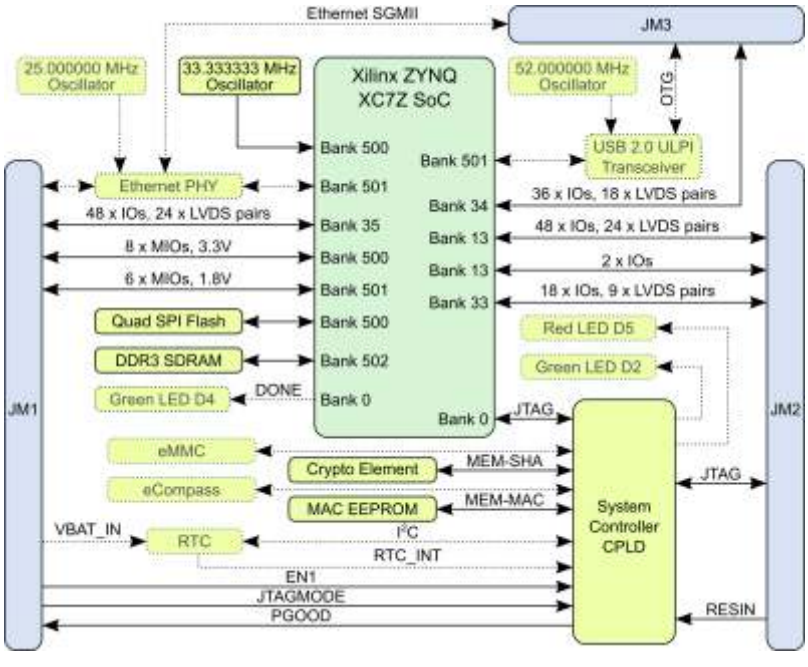
Extended device life cycle

Rugged for industrial applications

Key Features

- Industrial-grade Xilinx Zynq 7020 SoM, supported by the free Xilinx Vivado WebPACK tool
- Rugged for shock and high vibration
- ARM Dual Core Cortex-A9
- 10/100/1000 tri-speed gigabit Ethernet transceiver (PHY) with SGMII
  - MAC Address EEPROM
- 32-Bit-wide 1 GByte DDR3 SDRAM
- 32 MByte QSPI Flash memory (with XiP support)
- 4 GByte (up to 32 GB) e-NAND
- Plug-on module with 2 × 100-pin and 1 × 60-pin high-speed hermaphroditic strips
- 152 FPGA I/O's (75 LVDS pairs possible) and 14 PS-MIO available on board-to-board connectors
- USB 2.0 high-speed ULPI transceiver
- On-board high-efficiency DC-DC converters
  - 4.0 A x 1.0 V power rail
  - 1.5 A x 1.5 V power rail
  - 1.5 A x 1.8 V power rail
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Temperature compensated RTC (real-time clock)
- 3 user LEDs
- Optional MEMS sensor (3D accelerometer and 3D magnetometer)
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.



TE0728 Series

Xilinx Zynq, 2 × Cortex-A9, DDR3, Flash, 2 × Ethernet, CAN, Automotive

Overview

The Trenz Electronic TE0728-04-1Q is a SoC module integrating a Xilinx Automotive Zynq-7020, 512 MByte DDR3 SDRAM with 16-Bit width, 16 MByte Flash Memory for configuration and operation, two 100 Megabit Ethernet transceivers, and powerful switch-mode power supplies for all on-board voltages. A large number of con?gurable I/O's is provided via rugged high-speed stacking strips.

Within the complete module only Automotive components are installed. All this in a compact 6 x 6 cm form factor, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

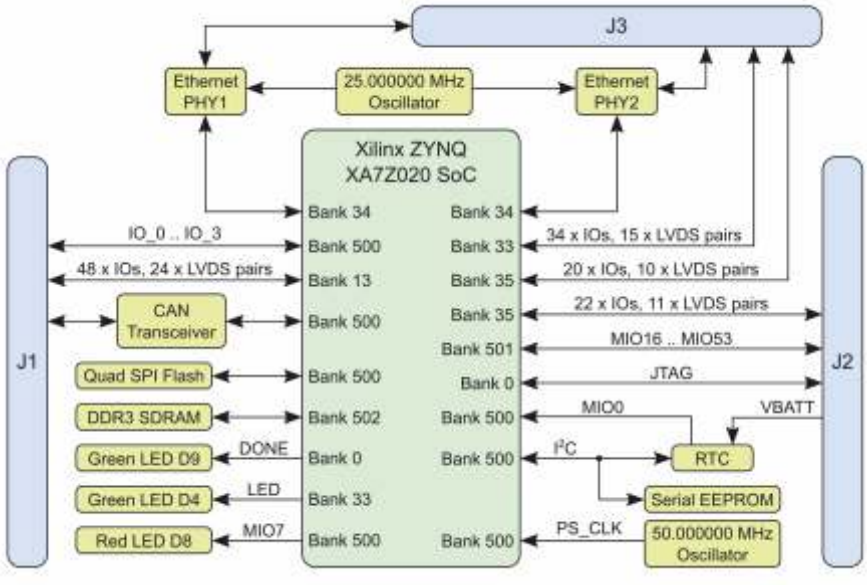
Extended device life cycle

Rugged for automotive applications

Key Features

- Xilinx Zynq XA7Z020-1CLG484Q (Automotive)
- Rugged for shock and high vibration
- 2 x ARM Cortex-A9 MPCore
- 2 x 100 MBit Ethernet transceiver (PHY)
- 16-Bit-wide 512 MByte DDR3 SDRAM
- 16 MByte QSPI Flash memory (with XiP support)
- Plug-on module with 3 x 80-pin high-reliability high-speed strips
- 76 single ended I/O, 24 LVDS pairs (48 I/O) and 42 MIO available on
- board-to-board connectors
- Board-to-board connectors
- CAN transceiver (PHY)
- Temperature compensated RTC (real-time clock)
- 12 V power supply with watchdog
- On-board high-efficiency DC-DC converters
- System management and power sequenci
- eFUSE bit-stream encryption
- AES bit-stream encryption
- 3 user LEDs
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0728

TE0782 Series

Xilinx Zynq, 2 × Cortex-A9, DDR3, Flash, 2 × GBit Ethernet, 2 × USB, 16 × Transceiver

8.5 form X factor 8.5

Overview

The Trenz Electronic TE0782 are industrial-grade SoC modules integrating a Xilinx Zynq-7 XC7Z035, XC7Z045 or XC7Z100, 1 GByte DDR3 SDRAM, 4 GByte eMMC, 16 GTX high-performance transceiver lanes, 32 MByte QSPI Flash memory for configuration and operation, and powerful switch-mode power supplies for all on-board voltages.

A large number of configurable I/O's is provided via rugged high-speed stacking strips. All this in a 8.5 x 8.5 cm form factor at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

Rugged for industrial applications

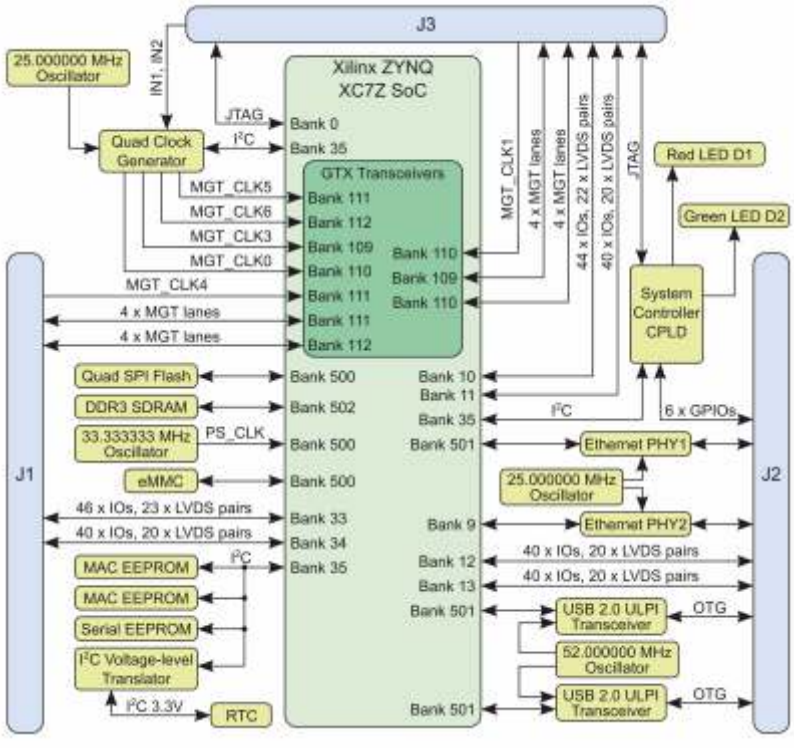
XILINX ALL PROGRAMMABLE™

ZYNQ™

Key Features

- Industrial-grade Xilinx Zynq-7 XC7Z035, XC7Z045 or XC7Z100 SOM
- Rugged for shock and high vibration
- Dual ARM Cortex-A9 MPCore
- Real Time Clock
- 2 x Hi-Speed USB2.0 ULPI Transceiver PHY
- 2 x Gigabit Ethernet Transceiver PHY
- 2 x Ethernet MAC Address EEPROM
- 1 GByte DDR3 SDRAM
- 32 MByte QSPI Flash memory
- 4 GByte eMMC (optional up to 64 GByte)
- Optional 2 x 8 MByte HyperRAM (max 2 x 32 MByte HyperRAM)
- Si5338 PLL for GTX clocking
- Plug-on module with 3 x 160-pin high-speed strips
- 16 GTX high-performance tranceiver lanes , GTX high-performance
- Transceiver clock input
- 254 FPGA I/O's (125 LVDS pairs possible) available on board-to-board connectors
- On-board high-efficiency DC-DC converters
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- Evenly spread supply pins for good signal integrity

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0782

TE0726 Series

Xilinx Zynq, 512 MByte DDR3L SDRAM, 16 MByte Flash, 100 MBit Ethernet RJ45

Overview

The Trenz Electronic TE0726 is a Rasberry Pi compatible FPGA module integrating a Xilinx Zynq-7010, 512 MByte DDR3L SDRAM, 4 USB ports, an Ethernet port and 16 MByte Flash memory for configuration und operation.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

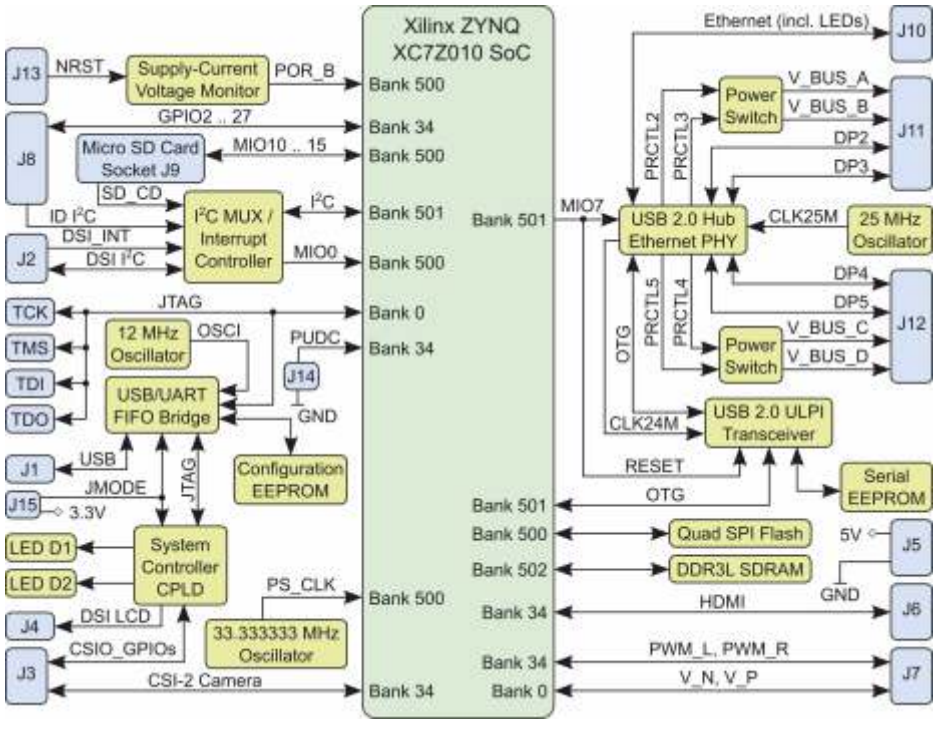
"Ideal for Maker" Make:

XILINX ALL PROGRAMMABLE™ ZYNQ™

Key Features

- Xilinx Zynq XC7Z010-1CLG225C
  - 512 MByte DDR3L SDRAM
  - 16 MByte Flash
- LAN9514 USB Hub with Ethernet
  - 4 x USB with power switches
  - 100 MBit Ethernet RJ45
- Micro SD card slot
- HDMI Typ A
- DSI Connector (Display)
- CSI-2 Connector (Camera)
- Micro USB
  - power input
  - USB UART
  - JTAG ARM- und FPGA-Debug
- 3.5 mm audio plug (PWM Audio output only)
- Raspberry Pi Model 2 form faktor
- HAT header with 26 I/O's

Other assembly options for cost or performance optimization plus high volume prices available on request.



www.trenz-electronic.de/te0726

TE0722 Series

Xilinx Zynq, Dual Core ARM A9+, 16 MByte SPI Flash, DIP40 Form Factor

1.8 form X factor 5.1

Overview

The DIPFORTy1 "Soft Propeller" is based on the Xilinx Zynq-7000, a System on Chip which contains a FPGA and a Dual Core ARM A9+ processor with enough logic gates to become a Propeller. The board also has 16 MByte of Flash used for configuration and everything fits on a Propeller-compatible DIP 40 pinout.
DIPFORTy1 "Soft-Propeller" is the lowest cost Zynq based module ever made and the first Zynq module that can use existing bases and project boards (Parallax Propeller chip compatibility). All this in a compact 1.8 x 5.1 cm form factor, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

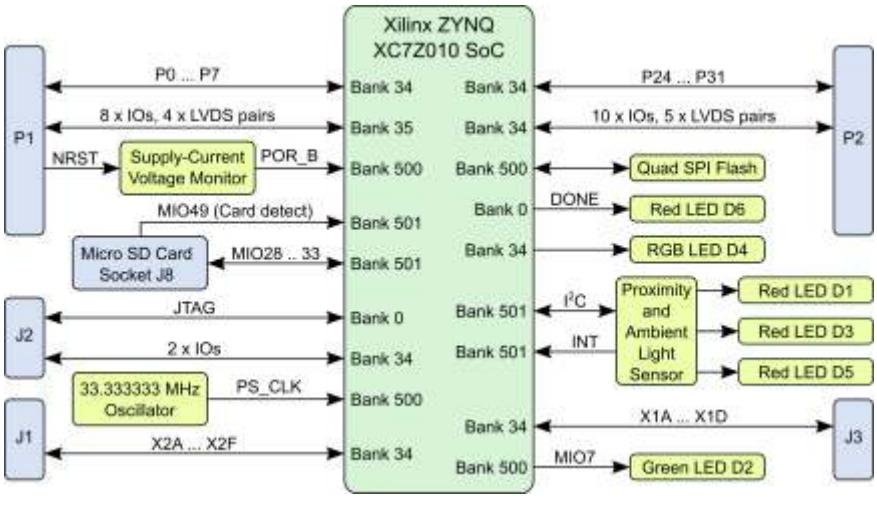
"Ideal for Maker" Make:

XILINX ALL PROGRAMMABLE™ ZYNQ™

Key Features

- Xilinx Zynq-7: XC7Z010-CLG225
  - 16 MByte SPI Flash (primary boot)
  - 33.333 MHz Clock (MEMS Oscillator)
- Dual Core ARM A9+
- DIP40 form factor
  - 2 x 20 holes for socket pins or pin-header
  - Size: 18 x 51 mm
- Total user accessible PL I/O: 46 (+3 Input only)
  - DIP40 header pins: 34 I/O
  - XMOD J1: 6 I/O
  - XMOD J2: JTAG + 2 I/O (or 3 input + 2 I/O)
  - XMOD J3: 4 I/O
- 3.3V single supply
- RGB LED (PL I/O connected)
- "Done" LED (inverted polarity)
- User LED (ARM CPU MIO GPIO)
- MicroSD Card socket (MIO, ZYNQ secondary boot media)
- Sil1143 Proximity and ambient light sensor

Other assembly options for cost or performance optimization available or high volume prices on request.



TE0741 Series

Xilinx Kintex-7 T, Flash, 8 × Transceiver

Overview

Trenz Electronic TE0741 are industrial-grade FPGA modules integrating a Xilinx Kintex-7 T FPGA, 32 MByte Flash memory for configuration and operation, 8 transceivers, and powerful switch-mode power supplies for all on-board voltages. A large number of configurable I/O's is provided via rugged high-speed stacking strips. All modules in 4 x 5 cm form factor are mechanically compatible.
All this on a tiny footprint, smaller than a credit card, at the most competitive price.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

Extended device life cycle

Rugged for industrial applications

Key Features

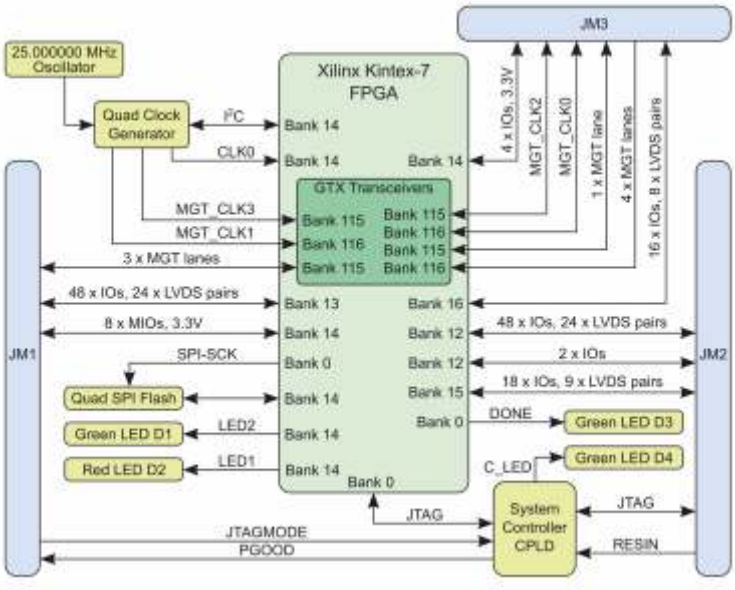
- Industrial-grade Xilinx Kintex-7 (70T, 160T, 325T and 410T) SoM
- Rugged for shock and high vibration
- 32 MByte QSPI Flash memory (with XiP support)
- Programmable clock generator
  - 2 x Transceiver clock (default 125 MHz)
  - Fabric clock (default 200 MHz)
- Plug-on module with 2 × 100-pin and 1 × 60-pin high-speed hermaphroditic strips
- 144 FPGA I/O's (65 LVDS pairs possible) available on board-to-board connectors
- 8 GTX (high-performance transceiver) lanes
  - GTX (high-performance transceiver) clock input
- On-board high-efficiency DC-DC converters
  - 20.0 A x 1.0 V power rail
  - 1.5 A x 1.8 V power rail
- System management and power sequencing
- eFUSE bit-stream encryption
- AES bit-stream encryption
- User LEDs
- Evenly spread supply pins for good signal integrity

Recommended Software:

- Kintex-7 XC7K**70T**-2CF, Kintex-7 XC7K**160T**-2CF: Xilinx Vivado Webpack (free license)

- Kintex-7 XC7K**325T**-2CF, Kintex-7 XC7K**410T**-2CF: Xilinx Vivado Design Suite

Other assembly options for cost or performance optimization plus high volume prices available on request.



TE0725 Series

Xilinx Artix-7, 32 MByte Flash, 87 IO's, 2x 50 Pin Headers 2.54 mm Pitch

Overview

The Trenz Electronic TE0725 is a low cost small-sized FPGA module integrating a Xilinx Artix-7 (15T - 100T) and 32 MByte Flash memory for configuration and operation. The 2 x 50 pin header with a 2.54 mm standard pitch fits perfect on a breadboard.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

XILINX ALL PROGRAMMABLE. ARTIX 7

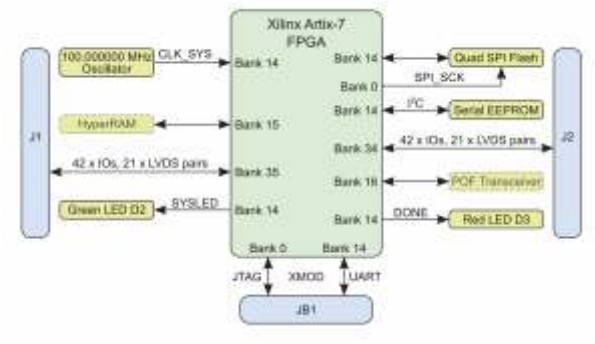
Extended device life cycle

Rugged for industrial applications

Key Features

- Xilinx Artix-7 15T up to 100T
- commercial temperature grade (industrial on request)
- 32 MByte Flash memory
- 2 x 50 pin headers with 2.54 mm pitch, ideal for breadboard use
- 87 IO's (42 + 42 + 3)
- 100 MHz system clock
- I2C EEProm
- 3.3V single supply with on board voltage regulators
- Size 73 x 35 mm
- JTAG connector
- 2 LEDs
- optional HyperRAM (8 to 32 MByte)
- optional Fiber Optic module

Other assembly options for cost or performance optimization available or high volume prices on request.



TE0725LP

Xmod Form-Factor, FT2232H, Lattice XO2-256 CPLD, 4 Position DIP Switch

Overview

The Trenz Electronic TE0725LP-01-100-2C is a low cost small-sized FPGA module integrating a Xilinx Artix-7 (15T - 100T) and 32 MByte Flash memory for configuration and operation. The 2 x 50 pin headers with a 2.54 mm standard pitch are perfect for bread-board or low cost dual layer PCB.

All modules produced by Trenz Electronic are developed and manufactured in Germany.

XILINX ALL PROGRAMMABLE. ARTIX 7

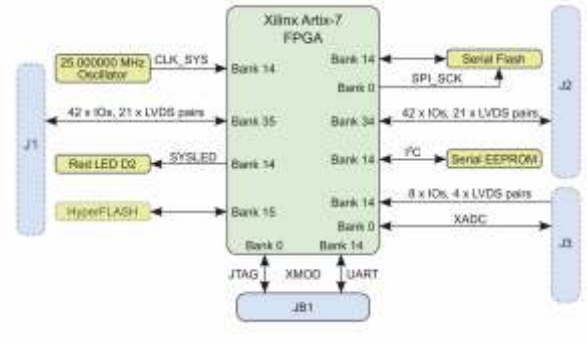
Extended device life cycle

Rugged for industrial applications

Key Features

- Xilinx Artix-7 XC7A100T
- commercial temperature grade (industrial on request)
- 32 MByte Flash memory
- 2 x 50 pin headers with 2.54 mm pitch, ideal for breadboard use
- 3.3 V or optional 1.8 V single supply with on board voltage regulators
- 95 I/O's (42 + 42 + 3 + 8)
- 25 MHz system clock (100 MHz can be customized on request)
- I2C EEPROM
- JTAG/UART connector
- One user LED
- 7.3 x 3.5 cm form factor
- Optional HyperRAM (8 - 32 MByte) or HyperFlash

Other assembly options for cost or performance optimization plus high volume prices available on request.



TE Carrier Boards
custom built for specific Trenz Electronic micromodules

Following Trenz Electronic Carrier Boards are custom-built base boards for specific Trenz Electronic SoMs, which exposes the module's B2B-connector-pins to accessible connectors and provides a whole range of on-board components to test and evaluate Trenz Electronic SoMs.

TEBF0808

- Mini-ITX form factor
- ATX power supply connector (Important 12 V only supply required)
- optional 12 V standard power plug
- USB 3.0 with USB 3.0 HUB
- Gigabit Ethernet RJ45
- MicroSD Card (bootable) and eMMC (bootable)
- PCIe slot - one PCIe lane (16 Lane connector)
- Displayport Single Lane
- One SATA Connector
- Dual SFP+
- FMC HPC slot (1.8 V max VCCIO)
- Fan connectors, PC enclosure, FMC fan
- Intel front panel- and HDA audio-connector
- CAN FD transceiver (10 pin IDC connector)
- 20 pins ARM JTAG connector (PS JTAG0)
- One Samtec FireFly (4 GT lanes bidir)
- One Samtec FireFly connector for reverse loopback

TEB0728

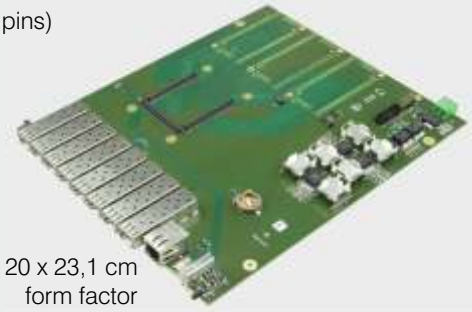
- Trenz TE0728 module socket (3 x Samtec SEM connectors 80 pins)
- 2 x RJ45 Ethernet
- SD card slot
- Power supply with DC jack
- 3 x user LED's (red/yellow/green)
- User push button

TEB0729

- Trenz TE0729 module socket (2 x Samtec BTE/BSE connectors 120 pins)
- 5 V board supply via DC jack
- 3 x RJ45 Ethernet
- 1 x MicroUSB and 1 x SD card connector
- 1 x 128K I2C CMOS Serial EEPROM
- 1 x 2K I2C Serial EEPROM
- XMOD (TE0790) pin header
- 2 x pin header FPGA bank power supply
- 1 x VBat pin header and 2 x VG96 pin header
- 1 x user push button, 1 x LED (red), user switch FPGA boot mode

TEB0745

- Trenz TE0745 module socket (3 x Samtec ST5 connectors 160 pins)
- 24 V power supply over ARKZ950/2 connecting terminal
- XMOD (TE0790) Pin Header (JTAG / UART)
- 1 x EMI Network Filter
- microSD connector
- RJ45 Ethernet connector
- USB Host connector
- 8 x SFP connector
- 6 x pin header 50 pol. (FPGA bank I/O's and power)
- 6 x pin header 12 pol. (FPGA bank I/O's and power)



20 x 23,1 cm
form factor

TEBA0714

- Trenz TE0714 module socket (2 x Samtec LSHM connectors 100 pins)
- XMOD (TE0790) pin header
- 1 x pin header 16 pol. (JTAG, MGT-CLK, boot mode, XADC, I/O's)
- 1 x pin header 10 pol. (I/O's)
- SFP connector
- LDO voltage regulator 3.3 V to 2.5 V
- 2 x user LED's (red/green) and 1 x LED (red)
- 2 x pin headers 50 pol. (FPGA bank I/O's and power)
- 1 x pin header for FPGA bank power VCCIO34 (1.8 VOUT, 2.5 V, 3.3 VOUT)
- 1 x pin header for FPGA bank power V_CFG (1.8 VOUT, 2.5 V, 3.3 VOUT)

TE0728	TE0729	TE0741	TE0745	TE0782	TE803	TE0808 „UltraSOM+“	TE820	TE0841
ZYNQ	ZYNQ	KINTEX 7	ZYNQ	ZYNQ	ZYNQ UltraSCALE+	ZYNQ UltraSCALE+	ZYNQ UltraSCALE+	KINTEX UltraSCALE
Z-7020 (automotive)	Z-7020	70T 160T 325T 410T	Z-7030 Z-7035 Z-7045	Z-7035 Z-7045 Z-7100	ZU3EG, ZU5EV, (ZU2CG-ZU5CG, ZU2EG-ZU5EG, ZU4EV, ZU5EV)	ZU9EG (ZU6CG, ZU9CG, ZU6EG, ZU9EG, ZU15EG)	ZU3EG, ZU5EV, (ZU2CG-ZU5CG ZU2EG-ZU5EG ZU4EV, ZU5EV)	KU35 KU40
6 form X factor 6	5.2 form X factor 7.6 *	4 form X factor 5	5.2 form X factor 7.6 *	8.5 form X factor 8.5	5.2 form X factor 7.6	5.2 form X factor 7.6	4 form X factor 5	4 form X factor 5
3 x Samtec SEM	2 x Samtec BTE	3 × Samtec LSHM	3 x Samtec ST5	3 x Samtec QTH	4 x Samtec ST5	4 x Samtec ST5	3 x Samtec LSHM	3 x Samtec LSHM
Artix-7	Artix-7	Kintex-7	Kintex-7	Kintex-7	UltraScale+	UltraScale+	UltraScale+	UltraScale
2 × Cortex A9	2 × Cortex A9	MicroBlaze	2 x Cortex A9	2 x Cortex A9	4 x Cortex A53+ 2 Cortex R5	4 x Cortex A53 + 2 Cortex R5	4 x Cortex A53+ 2 Cortex R5	MicroBlaze
512 DDR3	512 DDR3	-	1024 DDR3/L	1024 DDR3	8192 DDR4	8192 DDR4	4096 DDR4	4096 DDR4
16	32	32	32	32	64	64	64	32
8 KByte	3 x MAC	-	MAC	2 x MAC + 16 KByte	-	16 KByte	-	-
	4 - 64 GByte	-	-	4 - 64 GByte	-	-	4 - 64 GByte	-
2 x 100 MBit	2 x 100 MBit, 1 GBit	-	1 GBit	2 x 1 GBit	-	-	4 - 64 GByte	1 GBit
-	USB 2.0 OTG PHY	-	USB 2.0 OTG PHY	2 x USB 2.0 OTG	-	-	USB 2.0 OTG	-
124 + 34 MIO	136 + 14 MIO	144	250 + 6 MIO	250 + 2 MIO	156 + 65 MIO	204 + 65 MIO	132 + 14 MIO	144
-	-	8 x GTX	8 x GTX	16 x GTX	PS GTR 4	4 x GTR, 16 x GTH	PS GTR 4	8 x GTH
Automotive, RTC, CAN	RTC, Cooling Solution available	Programmable Clock Generator	RTC	Programmable Clock Generator, RTC, eMMC	Programmable Clock Generator	System Monitor, Programmable Clock Generator	Programmable Clock Generator, Real Time Clock, eMMC	Programmable Clock Generator

*modules with form factor 5.2. x 7.6 cm are not compatible with each other

EMC²-DP

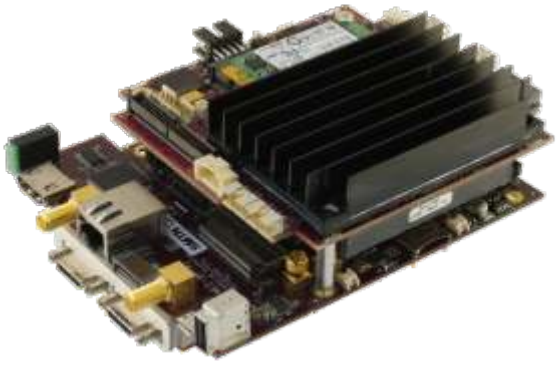
PC/104 OneBank Carrier for SoC Modules

www.sundance.technology/emc2-dp/

Providing the base for all of our PC/104 integrated systems the EMC²-DP is a PCIe/104 OneBank® Carrier for a Trenz compatible SoC Module and also has expansion for a VITA57.1 FMC™ LPC I/O board. It has I/O pins, using a 100-way Samtec RazorBeam connector system. The add-on board, called "Sundance External Interface Connector – SEIC" contains LEDs, RS232, USB2.0, HDMI, 1Gb Ethernet and SATA . The SEIC can be customized for individual applications with bespoke connectors.

The PCIe/104 OneBank® design enables the EMC²-DP to be added to robust and rugged installations for various commercial, medical, industrial and military uses.

- PCIe/104 OneBank® Carrier for Trenz SoC Modules
- PCI Express Gen 2 compatible and integrated PCI Express switch
- A number of EMC²-DP can be stacked for large I/O solutions
- Expandable with any VITA57.1 FMC I/O Module for more flexibility
- 96mm x 90 mm PC/104 Form-Factor with cable-less break-out PCB connector



oi110 - DUAL CAMERALINK

www.sundance.technology/oi110/

A dual lane CameraLink camera interface card (SMT-FMC521) and the EMC²-DP.
The integrated Xilinx FPGA allows any CameraLink format to connected to the oi110. Additional SATA-3 expansions allow connection to large storage for future processing.

- Dual CameraLink Ports
- Dual Single SATA-3 Ports
- PoCL (Power over Camera Link) support
- Up to 85MHz data rate
- Dual Base, Single Medium Base
- Single Extended Full CL Base

oi115 - HDMI IN / OUT

www.sundance.technology/oi115/

An HDMI in/out module and the EMC²-DP. As such this system gives you HDMI in and out on a one bank PC/104 FPGA carrier card.

- HDMI input/output FMC module (FMC-IMAGEON)
- HDMI input
- HDMI output
- Interface for ON Semiconductor VITA image sensor modules
- Video clock synthesizer

Xilinx development boards and kits provide an out-of-the box design solution to accelerate development time and time-to-market. Xilinx offers kits complete with evaluation boards, the Vivado Design Suite tools, IP cores, reference designs and FPGA Mezzanine Card (FMC) support – so application development begins immediately out of the box.

The Vivado Design Suite delivers a SoC-strength, IP-centric and system-centric, next generation development environment that has been built from the ground up to address the productivity bottlenecks in system-level integration and implementation.

Xilinx Zynq UltraScale+ MPSoC ZCU102 Evaluation Kit

The ZCU102 Evaluation Kit enables designers to jumpstart designs for Automotive, Industrial, Video and Communications applications. This kit features a Zynq UltraScale+™ MPSoC device with a quad-core ARM® Cortex-A53, dual-core Cortex-R5 real-time processors, and a Mali-400 MP2 graphics processing unit based on Xilinx's 16nm FinFET+ programmable logic fabric. The ZCU102 supports all major peripherals and interfaces enabling development for a wide range of applications.

Key Features & Benefits

- Optimized for quick application prototyping with Zynq Ultrascale+ MPSoC
- DDR4 SODIMM – 4GB 64-bit w/ ECC attached to Processor Subsystem (PS)
- DDR4 Component – 512MB 16-bit attached to Programmable Logic (PL)
- PCIe Root Port Gen2x4, USB3, Display Port & SATA
- 4x SFP+ cages for Ethernet
- 2x FPGA Mezzanine Card (FMC) interfaces for I/O expansion including 16 x 16.3 Gb/s GTH transceivers and 64 user defined differential I/O signals

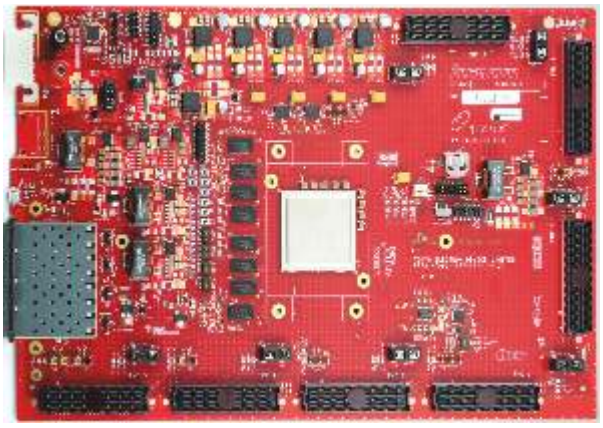
This is just one example of our wide variety of Boards and Kits from Xilinx. Please have a look in our online shop for a wider selection or ask for a quote at sales@trenz.biz.

Since 1965, Tokyo Electron Device Limited (TED) has been focused on the semiconductor distribution business. Leveraging 40 years of industry experience, in 2004, TED began offering FPGA solutions under the “inrevium” brand name.
Today, inrevium offers FPGA platform solutions, market specific IP, technical support, and design services to customers worldwide. Inrevium's domain-specific expertise, market knowledge, and pre-qualified solutions, resulted in inrevium being adorned with the prestigious Xilinx Alliance Program Member designation.

With design and development centers in Japan, China, and Canada, and a global network of sales offices, inrevium remains uniquely positioned to provide high-value design services. In addition to services, the development centers also create market-specific multi-million gate LSI devices, FPGA evaluation boards, FMC option cards, ASIC prototyping boards, drivers, firmware, and IP, to support a wide range of worldwide applications.

FPGA Evaluation Platforms

The inrevium Xilinx FPGA Evaluation Kits are special-purpose FPGA kits intended for use by design professionals, innovating and delivering stunning 3D, Organic Light Emitting Diode (OLED), Quad HD (4K2K resolution) and many other digital display technologies, as well as 3D TV broadcasting.



KINTEX UltraSCALE : 8K4K Image Evaluation Platform

FPGA Mezzanine Card (FMC) Standard

Developed by a consortium of companies ranging from FPGA vendors to end users, the FPGA Mezzanine Card is an ANSI standard that provides a standard Mezzanine Card form factor, connectors and modular interface to an FPGA located on a base board.

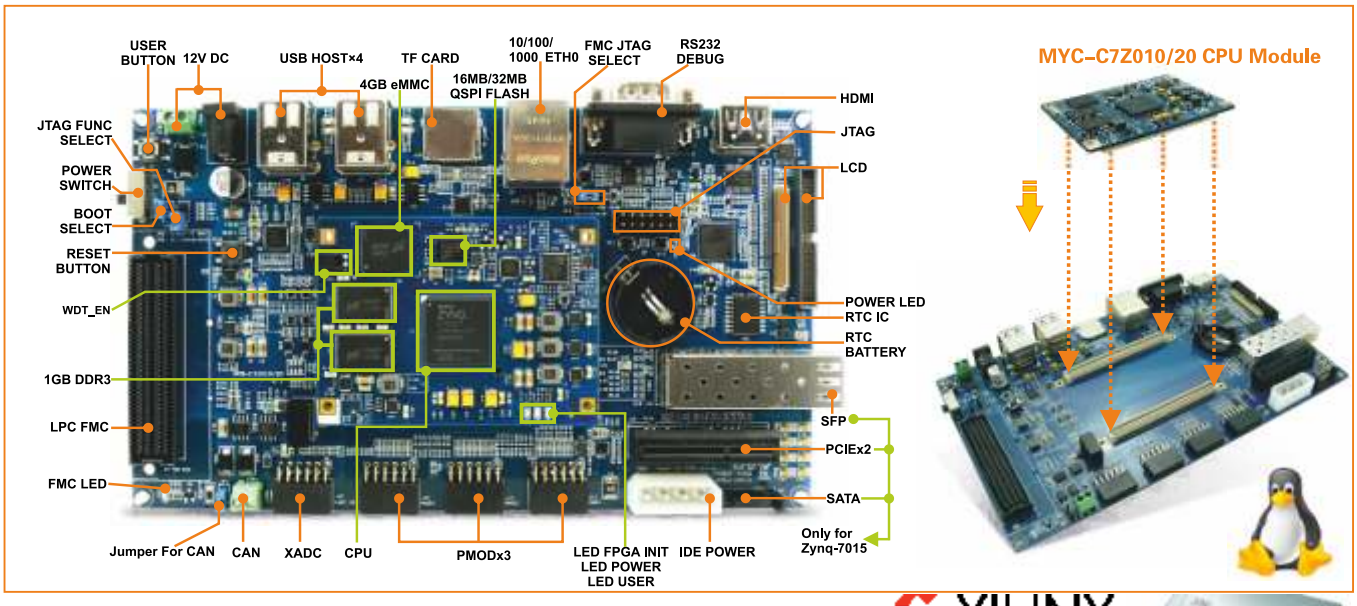
FMC is VITA 57 standard, provides a specification describing an I/O mezzanine module with connection to an FPGA or other device with reconfigurable I/O capability.

USB3.0 FMC Connectivity mezzanine card

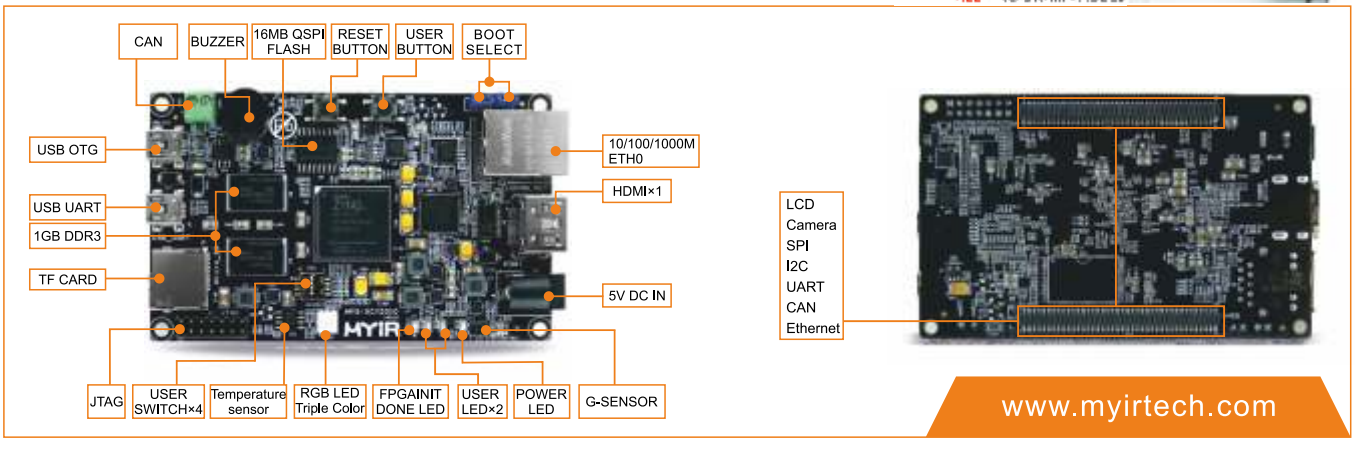
These are just selected examples of a wide variety of FPGA boards and FMC cards from inrevium.
Please have a look in our online shop or contact us at sales@trenz.biz
to get a quote for any available inrevium product.

MYIR Tech Limited is a global provider of ARM hardware and software tools, design solutions for embedded applications.
MYIR is an ARM Connected Community Member and work closely with ARM and many semiconductor vendors. They sell products ranging from board level products such as development boards, single board computers and CPU modules to help with your evaluation, prototype, and system integration or creating your own applications. Their products are used widely in industrial control, medical devices, consumer electronic, telecommunication systems, Human Machine Interface (HMI) and more other embedded applications. MYIR has an experienced team and provides custom services based on many processors (especially ARM processors) to help customers make your idea a reality.

MYD–C7Z010/20 Development Board



Z-turn Board



These are just selected examples of a variety of FPGA boards from MYIR. Please have a look in our online shop or contact us at sales@trenz.biz to get a quote for any available MYIR product.

cronologic

cronologic GmbH & Co. KG

cronologic offers a family of high-resolution high-throughput PCIe analog-to-digital converters (ADCs)

All models share these characteristics:

- 4 analog input channels
- Additional digital trigger and/or gating inputs
- PCIe x4 or x8 half-size boards
- Gross DMA-bandwidth of 1 Gbyte/s or 2 Gbyte/s
- Arbitrary board combinations can be synchronized
- LEMO 00 series input connectors (adapter cabels to SMA connector available)
- The DC-offset can be shiftet to make optimal use of the ADC range for either positiv or negative pulses

	Ndigo5G-10			Ndigo5G-8			Ndigo250M-14	Violet250M-14	Violet125M-14	unit
PCIe lanes	4			4			8	8	8	-
PCIe Bandwidth	800			800			1400	1400	1400	MB/s
Analog channels	4	2	1	4	2	1	4	4	4	-
Max. Sampling Rate	1250	2500	5000	1250	2500	5000	250	250	125	Msps
Max. Bandwidth	1000			1000			120 or 700	120 or 700	60 or 450	MHz
Max. individual sample length	26	26	26	26			32	hours	hours	µs
THD	58	58	58	58			73	73	86	dBc
SNR	51	50	50	45			64	64	74	dBc
SFDR incl.	61	60	60	58			74	74	86	dBc
SFDR excl.	74	64	63	57			76	76	TBD	dBc
SINAD	50	48	48	45			64	64	72	dBc
ENOB	8.0	7.7	7.7	7.2			10.3	10.3	11.0	-
Input type and coupling	AC single ended			AC single ended			DC single ended	DC single ended	DC single ended	-

Ndigo Series

It has been designed to aquire trains of pulses at high repetition rates. Employing an onboard zero supression, the pulse data is recorded with pre- and post-cursors, omitting the data inbetween to reduce the requirements on bandwidth and pulse processing or averaging. There is no deadtime between samples as long as the sustained rate is lower than the available PCIe bandwidth. The first available instances of this series provide 5 Gsps at 10-bit resolutuion and 250 Msps at 14-bit resolution.

These boards are ideally suited for applications like

- Mass Spectrometry
- Photon Counting
- Lidar
- NMR